

DP

PATENTS ONLY (ref OG 7/28/92)



To the Honorable Commis: Please record the attached

102368551

is:

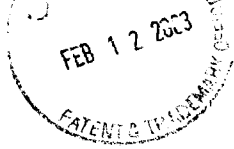
- 1. Name of Party(ies) conveying an interest: 2. Name and Address of Party(ies) receiving an interest:

Hirofaka NISHIZAWA, Hideki TANAKA Yuichiro YAMADA, Tomoaki KUDAISHI Akira KATSUMATA

HITACHI, LTD. 6, Kanda Surugadai 4-chome Chiyoda-ku, Tokyo, JAPAN

HITACHI ULSI SYSTEMS CO., LTD. 22-1, Josuihoncho 5-chome Kodaira-shi, Tokyo, JAPAN

SANWA DENKI KOGYO CO., LTD. 4-15-9, Nakano Nankano-ku, Tokyo, JAPAN



2-12-03

3. Description of the interest conveyed: Assignment

4. Application number(s) or patent number(s).

Additional sheet attached? Yes No

If this document is being filed together with a new application, the execution date of the application is:

DATE

- A. Patent Application No.(s) B. Patent No.(s)

10/240,111

5. Name and address of party to whom correspondence concerning document should be mailed:

John R. Mattingly Mattingly, Stanger & Malur, P.C. 1800 Diagonal Road, Suite 370 Alexandria, Virginia 22314

6. Number of applications and patents involved: One

7. Amount of fee enclosed or authorized to be charged: \$40.00

8. The Commissioner is hereby authorized to charge Deposit Account No. 50-1417 if no check is attached.

DO NOT USE THIS SPACE

02/19/2003 DBYRNE 00000036 10240111

01 FC:8021

40.00 DP

9. Execution date of attached document: September 2 & 4, 2002

10. To the best of my knowledge and belief, I declare under penalty of perjury under the laws of the United States of America that the foregoing information is true and correct and that any attached copy is a true copy of the original document.

Daniel J. Stanger Name of Person Signing

Signature

February 12, 2003 Date

Total number of pages being submitted: 3

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd., and SANWA DENKI KOGYO CO., LTD., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan, and 4-15-9, Nakano, Nakano-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd., and SANWA DENKI KOGYO CO., LTD., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A SEMICONDUCTOR DEVICE AND A METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be grant

the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd. and SANWA DENKI KOGYO CO., LTD., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd., and SANWA DENKI KOGYO CO., LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(發明者フルネームサイン)

Date Signed
(署名日)

- 1) Hiroataka Nishizawa Hiroataka NISHIZAWA 2/ September / 2002
- 2) Hideki Tanaka Hideki TANAKA 4/ September / 2002
- 3) yuichiro Yamada Yuichiro YAMADA 2/ september / 2002
- 4) Tomoaki Kudaishi Tomoaki KUDAISHI 4/ September / 2002
- 5) _____ Akira KATSUMATA _____
- 6) _____ _____
- 7) _____ _____
- 8) _____ _____
- 9) _____ _____
- 10) _____ _____

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd., and SANWA DENKI KOGYO CO., LTD., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan, and 4-15-9, Nakano, Nakano-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd., and SANWA DENKI KOGYO CO., LTD., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A SEMICONDUCTOR DEVICE AND A METHOD OF MANUFACTURING THE SAME invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd. and SANWA DENKI KOGYO CO., LTD., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd., Hitachi ULSI Systems Co., Ltd., and SANWA DENKI KOGYO CO., LTD.

Signed on the date(s) indicated beside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ HirotaKa NISHIZAWA	_____
2) _____ Hideki TANAKA	_____
3) _____ Yuichiro YAMADA	_____
4) _____ Tomoaki KUDAISHI	_____
5) <u>Akira Katsumata</u> Akira KATSUMATA	<u>24-Sep-2002</u>
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____